

COPYPATENTIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Jau-Yuen SU

Serial No.: 09/394,918

Group Art Unit: 3724

Examiner: O. Flores-Sanchez

Filed: September 13, 1999

Atty. Dkt.: SUJA3001/REF/WKP

For: PROCESS FOR SAWING SUBSTRATE STRIP

*Duplicate accepted
Mail date = 1/25/02*AMENDMENT AND RESPONSECommissioner for Patents
Washington, D.C. 20231Stephen Marcus
Special Program Examiner
Group 3700

Sir:

This is responsive to the Office Action mailed October 25, 2001 (Paper No. 12) in the above application. Reconsideration of the application is respectfully requested in view of the following amendments and remarks.

AMENDMENT

Please amend this application as follows:

IN THE CLAIMS

Please amend claim 9 as follows (an APPENDIX OF MARKED-UP AMENDED CLAIM is attached):

-9. (Twice Amended) The process as claimed in Claim 7, further comprising the step of cutting the substrate strip according to cutting tracks defined by the cutting marks parallel to the longitudinal axis.